

Wafer-Level Chip-Scale Packaging: Analog And Power Semiconductor Applications By Shichun Qu

By Shichun Qu

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Gave several keynotes and short courses in Analog and Power Packaging, Wafer Level Technology and Operations. Shichun Semiconductor. Jing Sun. Staff

<https://www.linkedin.com/pub/yong-liu/8/b19/ab>

Books by Yong Liu (Author of Advances in -

Symposium on Intelligence Computation and Applications, Wafer-Level Chip-Scale Packaging: Analog and Power Semiconductor Applications by Shichun Qu,

http://www.goodreads.com/author/list/437942.Yong_Liu

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